

Appl. No. 10/699,130
Amdt. Dated January 3, 2007
Reply to Office Action of August 31, 2006

• • REMARKS/ ARGUMENTS • •

This preliminary amendment is being submitted together with a Request for Continued Examination.

Initially applicant and the undersigned wish to express their appreciation to Examiner Daniels for scheduling a person interview on November 9, 2006.

At the interview, applicant demonstrated preforms and a mold set used to produce co-molded preforms and compared the preforms of the present invention with prior art encapsulated assemblies.

During the interview the parties discussed the Examiner's concerns as to applicable prior art of clam shell Styrofoam packaging designs. In addition, the parties discussed several features of applicant's invention which are considered to possibly distinguish over the prior art.

In particular, the Examiner suggested particular embodiments of the invention that were related to improved results in the field of use of applicant's invention. These embodiments are listed in the Interview Summary.

By the present amendment the limitations of dependent claim 11 have been incorporated into independent claim 9.

Inasmuch as claim 9 was objected to as being dependent upon a rejected base claim (i.e. claim 9), it is believed that, as presently amended, claim 9 and claims 10, and 12-20 which depend therefrom are each in condition for allowance.

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Also by the present amendment, independent claim 1 has been changed to recite "embedding a reinforcing insert into at least one of the first and second molded forms," and claim 22 which depends from claim 1 has been added which recites that "the reinforcing insert comprises at least one of a scrim, an emi shield and a heat sink."

In addition, new claim 23 has been added which a method of protecting an electrical assembly having a plurality of electrical components assembled on a circuit board, including the reuse of the molded forms and how the molded forms absorb vibrations and shock and/or conduct thermal effects from the electrical assembly.

Claim 23 was intended to cover the method of making or protecting an electrical assembly involving the features of the invention which were discussed at the interview and contrasted to the prior art. That is, the prior art encapsulation methods do not allow for removal and reuse of the encapsulation materials nor the use of encapsulation materials that absorb vibration or shock or transmit thermal effects.

To further distinguish applicant's invention over the prior art, claim 23 recites that individual ones of the electrical components that are assembled on the circuit board are received in separate recesses formed in the first molded form that are complementarily shaped to individual ones of the electrical components.

The pending claims are believed to distinguish over the prior art for reasons discussed at the interview.

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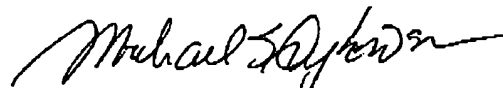
Entry of the present preliminary amendment and an early examination of the application are earnestly solicited.

It is believed that the above represents a complete response to the outstanding Official Action and reconsideration is requested.

If upon consideration of the above, the Examiner should feel that there remain outstanding issues in the present application that could be resolved, the Examiner is invited to contact applicant's patent counsel at the telephone number given below to discuss such issues.

To the extent necessary, a petition for an extension of time under 37 CFR §1.136 is hereby made. Please charge the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 12-2136 and please credit any excess fees to such deposit account.

Respectfully submitted,



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